Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (DTMOS

# **TK20J60U**

### **Switching Regulator Applications**

• Low drain-source ON resistance: RDS (ON) = 0.165 (typ.)

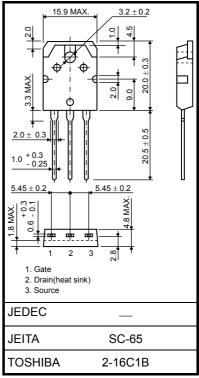
• High forward transfer admittance:  $|Y_{fS}| = 12 \text{ S (typ.)}$ 

• Low leakage current:  $I_{DSS} = 100 \mu A (V_{DS} = 600 V)$ 

• Enhancement-mode:  $V_{th} = 3.0 \sim 5.0 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_{D} = 1 \text{ mA}$ )

#### **Absolute Maximum Ratings (Ta = 25°C)**

| Characteristics                        |                              | Symbol           | Rating     | Unit |  |
|--|------------------------------|------------------|------------|------|--|
| Drain-source voltage                   |                              | $V_{DSS}$        | 600        | V    |  |
| Gate-source voltage                    |                              | V <sub>GSS</sub> | ±30        | V    |  |
| Drain current                          | DC (Note 1)                  | I <sub>D</sub>   | 20         |      |  |
|  | Pulse (t = 1 ms)<br>(Note 1) | I <sub>DP</sub>  | 40         | Α    |  |
| Drain power dissipation (Tc = 25°C)    |                              | P <sub>D</sub>   | 190        | W    |  |
| Single pulse avalanche energy (Note 2) |                              | E <sub>AS</sub>  | 144        | mJ   |  |
| Avalanche current (Note 3)             |                              | I <sub>AR</sub>  | 20         | Α    |  |
| Repetitive avalanche energy            |                              | E <sub>AR</sub>  | 19         | mJ   |  |
| Channel temperature                    |                              | T <sub>ch</sub>  | 150        | °C   |  |
| Storage temperature range              |                              | T <sub>stg</sub> | -55 to 150 | °C   |  |



Weight: 4.6 g (typ.)

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Note:

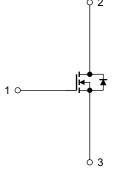
| Characteristics                        | Symbol                 | Max   | Unit |  |
|--|------------------------|-------|------|--|
| Thermal resistance, channel to case    | R <sub>th (ch-c)</sub> | 0.658 | °C/W |  |
| Thermal resistance, channel to ambient | R <sub>th (ch-a)</sub> | 50    | °C/W |  |

Note 1: Please use devices on conditions that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 0.63 mH,  $R_G$  = 25 ,  $I_{AR}$  = 20 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



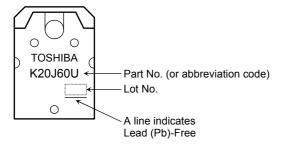
## Electrical Characteristics (Ta = 25°C)

| Chara                        | acteristics    | Symbol               | Test Condition  | Min | Тур.  | Max  | Unit |
|------------------------------|----------------|----------------------|---|-----|-------|------|------|
| Gate leakage current         |                | I <sub>GSS</sub>     | $V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$   | _   | _     | ±1   | μА   |
| Drain cut-off current        |                | I <sub>DSS</sub>     | V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V  | _   | _     | 100  | μА   |
| Drain-source brea            | akdown voltage | V (BR) DSS           | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V   | 600 | _     | _    | V    |
| Gate threshold vo            | oltage         | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA   | 3.0 | _     | 5.0  | V    |
| Drain-source ON              | resistance     | R <sub>DS</sub> (ON) | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A   | _   | 0.165 | 0.19 | Ω    |
| Forward transfer             | admittance     | Y <sub>fs</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 A   | 3.0 | 12    | _    | S    |
| Input capacitance            |                | C <sub>iss</sub>     |   | _   | 1470  | _    |      |
| Reverse transfer capacitance |                | C <sub>rss</sub>     | V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz  | _   | 150   | _    | pF   |
| Output capacitance           |                | C <sub>oss</sub>     |   | _   | 3500  | _    |      |
| Switching time               | Rise time      | t <sub>r</sub>       | 10 V ID = 10A VOUT  | _   | 40    | _    |      |
|                              | Turn-on time   | t <sub>on</sub>      | $\begin{array}{c c}  & & \\ $ | _   | 80    | _    | . ns |
|                              | Fall time      | t <sub>f</sub>       |   |     | 12    |      |      |
|                              | Turn-off time  | t <sub>off</sub>     | Duty $\leq$ 1%, t <sub>W</sub> = 10 μs  |     | 100   |      |      |
| Total gate charge            |                | Qg                   |   | _   | 27    | _    |      |
| Gate-source charge           |                | Q <sub>gs</sub>      | $V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$   | _   | 16    | _    | nC   |
| Gate-drain charge            |                | Q <sub>gd</sub>      |   |     | 11    | _    |      |

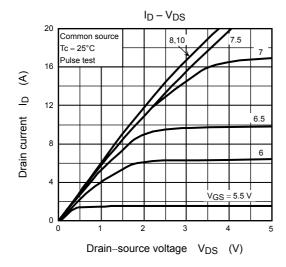
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

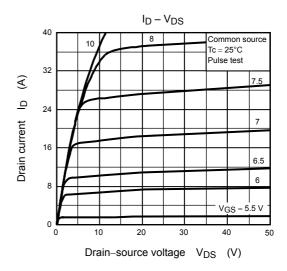
| Characteristics                           | Symbol           | Test Condition                                 | Min | Тур. | Max  | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | _  | _   | _    | 20   | Α    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> | _  | _   | _    | 40   | Α    |
| Forward voltage (diode)                   | V <sub>DSF</sub> | I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0 V  | _   | _    | -1.7 | V    |
| Reverse recovery time                     | t <sub>rr</sub>  | I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0 V, | _   | 450  | _    | ns   |
| Reverse recovery charge                   | Q <sub>rr</sub>  | dI <sub>DR</sub> /dt = 100 A/μs                | _   | 8.1  | _    | μС   |

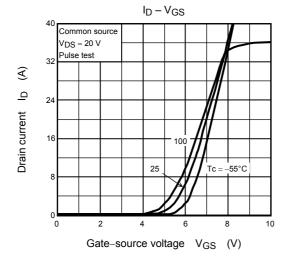
## Marking

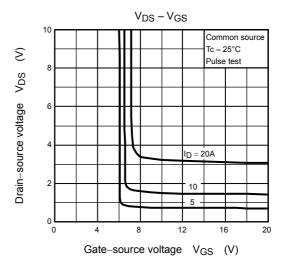


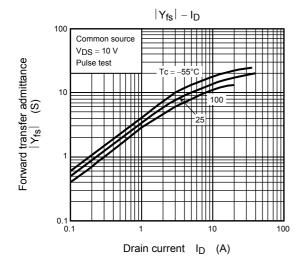
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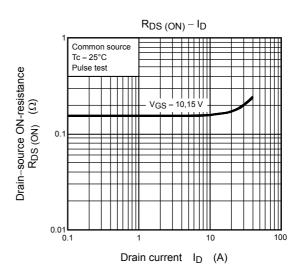


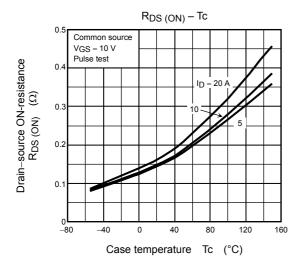


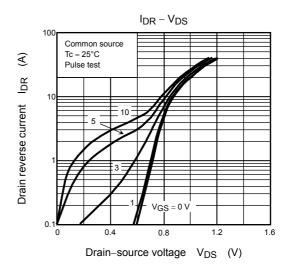


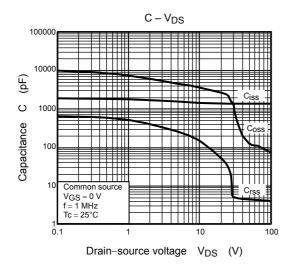


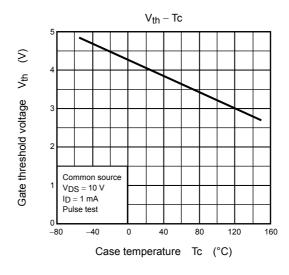


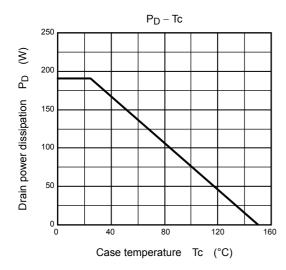


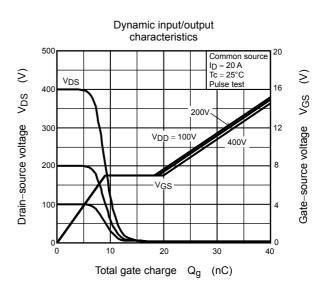




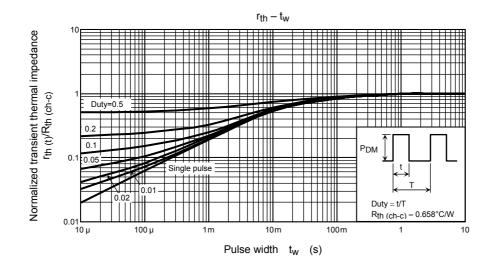


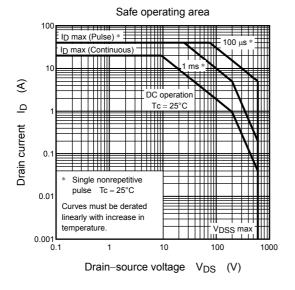


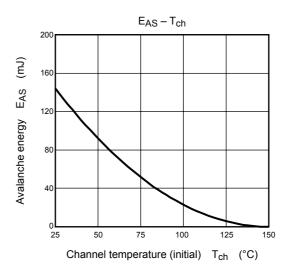


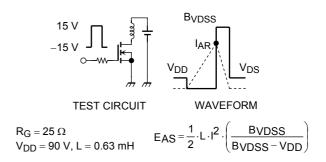


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